

Sensors and Materials

Special Issue on Artificial Intelligence in Sensing Technologies and Systems

Call for Papers

Recently artificial intelligence (AI) and machine learning (ML) have achieved state-of-the-art performance in a lot of difficult tasks and facilitated the creation of new products and services in many different fields. Now sensing technologies and sensing systems are undergoing massive expansion and development, and the combination of AI and sensors will become very common. In this Special Issue, we invite the submission of original research results regarding AI and advanced technologies for sensing technologies and systems. Potential topics of interest for publication include but are not limited to the following:

Scope:

- Sensing technologies
- Sensing systems
- Smart sensor devices
- Machine learning
- Engineering optimization
- Sensor data analysis
- Internet of Things
- Sensor networks
- Medical and health
- Signal and image processing
- Environmental monitoring
- AI in materials

Submission due date: June 30, 2020

Publication date (planned): Second half of 2020 or first half of 2021

Journal website: <https://myukk.org/>

Guest Editor: Prof. Lin Lin (Dalian University of Technology)

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(Attention)

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If you have any questions, please feel free to contact the editorial staff at the address below.

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